

Abstract

To improve peel stability of a carrier foil after press-forming at a temperature higher than 300°C, poor peel stability being a drawback of conventional electrodeposited copper foils with peelable carrier, and to provide an electrodeposited copper foil with carrier in which a carrier foil can be peeled stably by application of a small peel force. The objects are attained by use of an electrodeposited copper foil with peelable carrier in which an adhesive interface layer is formed on a carrier foil by use of thiocyanuric acid and an electrodeposited copper foil layer 5 is deposited on the adhesive interface layer.